

Amendments to the Claims

1. (Currently amended) An electronic control module, comprising:
a housing having a first aperture; and
a substrate disposed within the housing and having a second aperture positioned adjacent to the first aperture, and including a hydrophobic vent assembly disposed over the second aperture and adheringly coupled to the substrate, and adapted to permit egress with respect to the housing of a gas therethrough,
wherein at least one electrical component located on the substrate electrically couples to ground via an electrical pathway extending through the second aperture, the electrical pathway being electrically coupled to the housing.
2. (Original) The module as recited in claim 1, wherein the hydrophobic vent assembly comprises a fluorinated polymer membrane coupled to a structural screen.
3. (Original) The module as recited in claim 3, wherein the fluorinated polymer comprises GORE-TEX®.
4. (Currently amended) The module as recited in claim [[1]] 2, wherein the structural screen is a 180-mesh copper soldered to the substrate.
5. (Currently amended) An electronic control module, comprising:
a housing having a first aperture; and

a substrate disposed within the housing and having a second aperture positioned adjacent to the first aperture, and including a hydrophobic vent assembly disposed over the second aperture and adheringly coupled to the substrate, and adapted to permit egress with respect to the housing of a gas therethrough,

wherein the hydrophobic vent assembly comprises a hydrophobic coating disposed over a structural screen, wherein the structural screen is coupled to the substrate.

6. (Original) The module as recited in claim 5, wherein the hydrophobic coating comprises Wacker Semicosil 964®.

7. (Cancelled)

8. (Original) The module as recited in claim 1, wherein the hydrophobic vent assembly is adheringly coupled to the substrate via solder.

9-41. (Cancelled)

42. (New) The module as recited in claim 5, wherein the hydrophobic vent assembly is adheringly coupled to the substrate via solder.

43. (New) The module as recited in claim 5, wherein the structural screen is a 180-mesh copper soldered to the substrate.